What is claimed is:

1. Ceramic powder having a multi-peak frequency distribution pattern having at least two peaks as a particle size distribution as determined using a laser diffraction-scattering type particle size-analyzer, the maximum particle size for the first peak ranging from 40 to 80 μ m and that for the second peak ranging from 3 to 8 μ m and the rate of the particles having a particle size of not less than 20 μ m and less than 40 μ m being not more than 20% by mass (inclusive of 0% by mass).

2. The ceramic powder as set forth in claim 1, further having a third peak whose maximum particle size ranges from 0.1 to 0.8 μ m.

3. The ceramic powder as set forth in claim 1 or 2, having a chemical absorption amount of ammonia ranging from 0.1 to 1.8 μ mole/g.

4. The ceramic powder as set forth in any one of claims 1 to 3, being silica powder.

5. The ceramic powder as set forth in claim 4, having an Al_2O_3 content ranging from 100 to 8000 ppm.

6. A composition comprising at least one of a resin and rubber and the ceramic powder as set forth in any one of claims 1 to 5, incorporated therein.

7. A semiconductor-sealing material comprising the composition as set forth in claim 6, wherein at least one of the resin and rubber is an epoxy resin.

Claims

1. Ceramic powder having a multi-peak frequency distribution pattern having at least two peaks as a particle size distribution as determined using a laser diffraction-scattering type particle size-analyzer, the maximum particle size for the first peak ranging from 40 to 80 μm and that for the second peak ranging from 3 to 8 μm, the rate of the particles having a particle size of not less than 20 μm and less than 40 μm being not more than 20% by mass (inclusive of 0% by mass) and the ceramic powder having a chemical absorption amount of ammonia ranging from 0.1 to 1.8 μmole/g.

2. The ceramic powder as set forth in claim 1, further having a third peak whose maximum particle size ranges from 0.1 to 0.8 μm.

3. The ceramic powder as set forth in claim 1 or 2, being silica powder.

4. The ceramic powder as set forth in claim 3, having an Al_2O_3 content ranging from 100 to 8000 ppm.

5. A composition comprising at least one of a resin and rubber and the ceramic powder as set forth in claim 1, incorporated therein.

6. A semiconductor-sealing material comprising the composition as set forth in claim 5, wherein at least one of the resin and rubber is an epoxy resin.